

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application of ) Attorney Docket No.: **MIYOSH0006**  
Kazuyoshi TENDOU et al. )  
Serial No.: 10/596,387 ) Confirmation No.: 5987  
Filed: April 13, 2007 )  
For: EPOXY RESIN MOLDING ) Group Art Unit: 1796  
MATERIAL FOR SEALING AND )  
ELECTRONIC COMPONENT ) Examiner: Michael J. FEELY  
                            ) Date: September 16, 2009  
                            )

**AMENDMENT (B)**

**MAIL STOP: AMENDMENT**  
U.S. Patent and Trademark Office  
Customer Service Window  
Randolph Building  
401 Dulany Street  
Alexandria, VA 22314

Sir:

In response to the non-final Office Action mailed June 22, 2009, please amend the application identified above as follows:

**Amendments to the Claims** are reflected in the listing of claims, which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 5 of this paper.